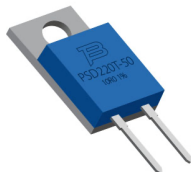


MATERIAL DECLARATION SHEET



Material Number	PSD220T-50 Series			
Product Line	Fixed Resistors			
Compliance Date	2025/10/27			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Plating	Tin Plating	2.4	Tin	7440-31-5	57.97	0.111	0.122
			0.2	Copper	7440-50-8	4.83	0.009	
			0.04	Silver	7440-22-4	0.97	0.002	
		Nickel Plating	1.5	Nickel	7440-02-0	36.23	0.069	0.069
2	Leads	Copper	148.5	Copper	7440-50-8	100%	6.841	6.841
3	Inside Soldering	Tin solder	134.4	Tin	7440-31-5	90.9	6.192	6.812
			11.2	Copper	7440-50-8	7.58	0.516	
			2.24	Silver	7440-22-4	1.52	0.103	
4	Heatsink	Copper Plate	1350	Copper	7440-50-8	100	62.195	62.195
5	Heatsink Plating	Nickel Plating	1	Nickel	7440-02-0	100	0.046	0.046
6	Substrate	Ceramic	115.68	Alumina	1344-28-1	99.6	5.307	5.329
				Silicon Dioxide	7631-86-9	0.4	0.022	

MATERIAL DECLARATION SHEET



7	Coating	Epoxy	1.28	Brominated Epoxy Oligomer	68928-70-1	100	0.059	0.059
8	Resistor Material	Thick film	2.02	Silver	7440-22-4	21.4	0.020	0.093
				Platinum	7440-06-4	29.7	0.028	
				Lead Monoxid	1317-36-8	10.4	0.010	
				Silicon Dioxide	7631-86-9	15.6	0.015	
				Ruthenium Oxide	12036-10-1	10.4	0.010	
				Ruthenium Dioxide	12036-10-1	7	0.006	
				Lead Ruthenium Oxid	37194-88-0	5.5	0.005	
9	Cover film	Glass layer	0.12	Lead bisilicate	65997-18-4	100	0.006	0.006
10	Mold	Fortron 1140L4	400	Polyphenylensulfid	26125-40-6	100	18.428	18.428
		Total weight	2170.58					

This Document was updated on: 2025/10/27

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Resistive material weight will be different based on the resistance value.
3. The weight of the core and coating material will differ based on the size.